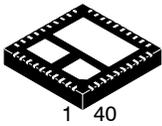


MECHANICAL CASE OUTLINE

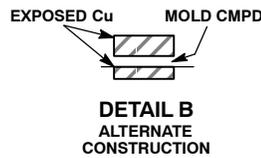
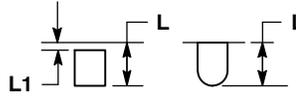
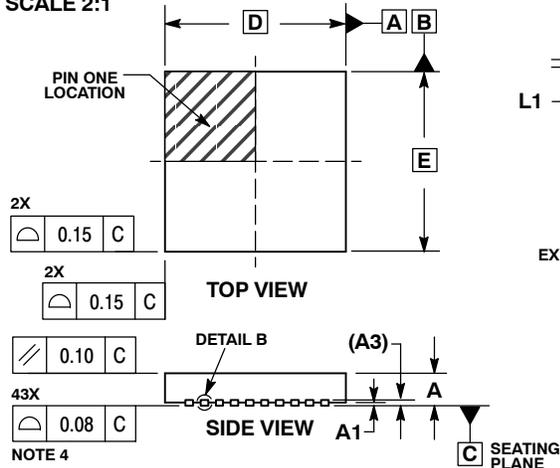
PACKAGE DIMENSIONS

ON Semiconductor®



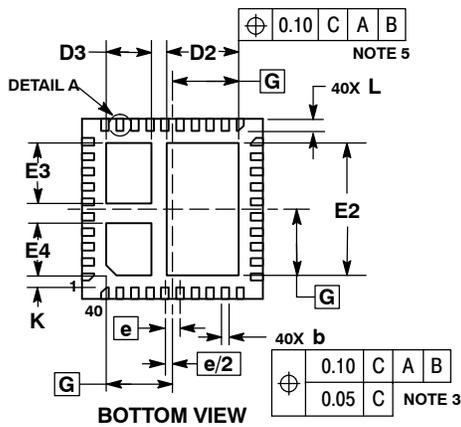
QFN40 6x6, 0.5P
CASE 485CM
ISSUE O

DATE 05 JUN 2012

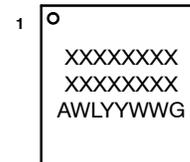


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSIONS: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
 5. POSITIONAL TOLERANCE APPLIES TO ALL THREE EXPOSED PADS.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	---	0.05
A3	0.20	REF
b	0.18	0.30
D	6.00	BSC
D2	2.30	2.50
D3	1.40	1.60
E	6.00	BSC
E2	4.30	4.50
E3	1.90	2.10
E4	1.64	1.84
e	0.50	BSC
G	2.20	BSC
K	0.20	---
L	0.30	0.50
L1	---	0.15

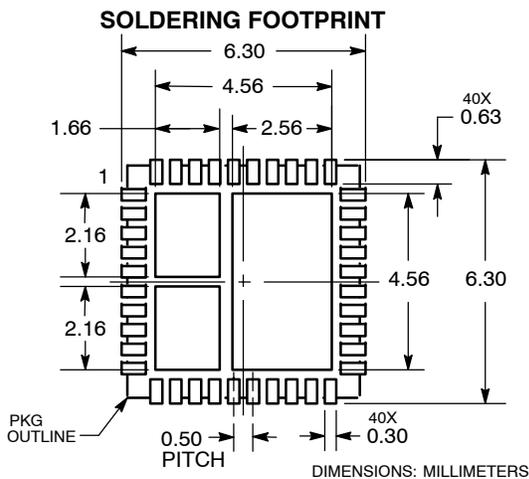


GENERIC MARKING DIAGRAM*



- XXXXXX = Specific Device Code
 A = Assembly Location
 WL = Wafer Lot
 YY = Year
 WW = Work Week
 G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "μ", may or may not be present.



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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	QFN40 6x6, 0.5P	PAGE 1 OF 2

